



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-11-14
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	IYWY*UY13AAA	A	ZS1A	2013-11-14
Amount	UoM	Unit type	ST ECOPACK Grade	
16.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	2.8 - 2.6 - 0.9	5	gull wing	
Comment	Package: SOT 23-5; MDF valid for TSX561A1LT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IYWY*UY13AAA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.82	mg	supplier	die	Silicon (Si)	7440-21-3		0.795	mg	969512	49688
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	4878	250
Silicon Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	2439	125
Silicon Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.002	mg	2439	125
Silicon Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.01	mg	12195	625
Silicon Die				supplier	passivation	Gamma-butyrolactone	96-48-0		0.005	mg	6098	313
Silicon Die				supplier	passivation	Polyhydroxyamide	55295-98-2		0.002	mg	2439	125
Lead-frame	Copper & its alloys	7.2	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.936	mg	963333	433500
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		0.162	mg	22500	10125
Lead-frame				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	278	125
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.009	mg	1250	563
Lead-frame				supplier	metallization	Nickel (Ni)	7440-02-0		0.083	mg	11528	5188
Lead-frame				supplier	metallization	Palladium (Pd)	7440-05-3		0.007	mg	972	438
Lead-frame				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	139	63
Die Attach	Other Organic Material	0.07	mg	Supplier	Glue	Epoxyde Bisphenol A Resin	25068-38-6		0.02	mg	285714	1250
Die Attach				Supplier	Glue	Aromatic amine	Proprietary		0.003	mg	42857	188
Die Attach				Supplier	Glue	Glycol ether ester	Proprietary		0.003	mg	42857	188
Die Attach				Supplier	Glue	silica	60676-86-0		0.021	mg	300000	1313
Die Attach				Supplier	Glue	Aluminium oxide	1344-28-1		0.023	mg	328571	1438
Bonding Wire	Other Inorganic Material	0.15	mg	Supplier	Bonding Wire	Gold (Au)	7440-57-5		0.15	mg	1000000	9375
encapsulation	Other Inorganic Material	7.76	mg	supplier	mold compound	Silica, vitreous	60676-86-0		6.619	mg	852964	413688
encapsulation				supplier	mold compound	phenolic resin	Proprietary		0.272	mg	35052	17000
encapsulation				supplier	mold compound	epoxy resin	Proprietary		0.31	mg	39948	19375
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.155	mg	19974	9688
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.016	mg	2062	1000
encapsulation				supplier	mold compound	Zinc hydroxide	20427-58-1		0.078	mg	10052	4875
encapsulation				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.31	mg	39948	19375